IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information				
upplier Infor	mation				•				·					
Company name*			Company unique ID			Ţ	Unique ID Authority				Response Date*			
nsemi											2023-06-08			
Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	ion Manufacturing Site		V	Veight*	UOM	Unit Type
		NCV57302DSADJR4 3A		3A ADJ VLDO REGULATOR			2023-06-08		N	MY1		617.9136	mg	Each
Ianufacturin g	g Proccess Informat	tion												
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-	STD-020 MSI	220 MSL Rating Peak Process Body Temperature Max Time at Peak Tempe					Temperatu	re Numbe	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy 1				260	C		30	second	ls 3			
omments											-			
	time at peak temperatu	re during sol	dering is 10-3	0 seconds										
or more informa	tion regarding material	composition	nlease refer to	nage 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	A	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	851.27	mg	В	Nickel (Ni)	7440-02-0		2.5538	mg
			Supplier	Copper (Cu)	7440-50-8		848.7162	mg
Mold Compound-Black	727.2536			Epoxy resin	proprietary data		36.3627	mg
			Supplier	Phenolic Resin	Proprietary Data		36.3627	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		14.5451	mg
			Supplier	Carbon Black (C)	1333-86-4		3.6363	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		636.3469	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg